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Product Change Notification - RMES-05VMLN744

Date: 15 Dec 2016
Product Category: Analog (Thermal, Power Management & Safety)
Notification subject: CCB 2811 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected R&E Products available in 16L SOIC package at MMT assembly site.
Notification text: **PCN Status:**
 Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected R&E Products available in 16L SOIC package at MMT assembly site.

Pre Change:

Gold (Au) bond wire

Post Change:

Palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MMT	MMT
Wire material	Au	CuPdAu
Die attach material	2200D	2200D
Molding compound material	G600V	G600V
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:

None

Reason for Change:

To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

February 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date.

Time Table Summary:

	December 2016					->	February 2017				
Work Week	48	49	50	51	52		5	6	7	8	9
Initial PCN Issue Date			X								
Qualification Report Availability										X	
Final PCN Issue Date										X	

Markings to Distinguish Revised from Unrevised Devices:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:
December 15, 2016: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):
[PCN_RMES-05VMLN744_Affected_CPN.pdf](#)
[PCN_RMES-05VMLN744_Qual Plan.pdf](#)
[PCN_RMES-05VMLN744_Affected_CPN.xlsx](#)

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PCN_RMES-05VMLN744 CCB 2811 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected RE Products available in 16L SOIC package at MMT assembly site.

Affected Catalog Part Number

PCN_RMES-05VMLN744
CATALOG_PART_NBR
RE280S16TF
RE296S16F
RE296S16TF
RE297S16F
RE297S16TF
RE298S16F
RE298S16TF
RE299S16F
RE299S16TF
RE320S16F
RE320S16TF
RE321S16F
RE321S16TF
RE340S16F
RE340S16TF
RE342S16F
RE342S16TF
RE46C107S16F
RE46C107S16TF
RE46C109S16F
RE46C109S16TF
RE46C119S16F
RE46C119S16TF
RE46C140S16F
RE46C140S16TF
RE46C141S16F
RE46C141S16TF
RE46C143S16F
RE46C143S16TF
RE46C144S16F
RE46C144S16TF
RE46C145S16F
RE46C145S16F-AAA
RE46C145S16TF
RE46C145S16TF-AAA
RE46C165S16F
RE46C165S16TF
RE46C166S16F
RE46C166S16TF
RE46C167S16F
RE46C167S16TF
RE46C168S16F

PCN_RMES-05VMLN744 CCB 2811 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected RE Products available in 16L SOIC package at MMT assembly site.

Affected Catalog Part Number

PCN_RMES-05VMLN744
CATALOG_PART_NBR
RE46C168S16TF
RE46C180S16F
RE46C180S16TF
RE46C190S16F
RE46C190S16TF
RE46C191S16F
RE46C191S16TF